

APPENDIX

Amendments to the Claims:

The following listing of claims will replace any/all prior versions, and listings, of claims in the application, wherein additions are shown in underlined text and deletions are shown in strike-out text:

1. (Currently amended) A batch type atomic layer deposition apparatus, comprising:

a ~~reaction~~ reaction chamber having a predetermined volume constituted with an upper plate, a lower plate and sidewalls;

a rotating plate loaded with a plurality of wafers, wherein each wafer is located in the reaction chamber and loaded radially at a predetermined position disposed in an identical distance from a center of the rotating plate;

a radial shower head having a cylinder part and a radial cone part for forcing a gas to flow toward an upper surface of the wafer as passing through a center of the upper plate, wherein the radial shower head faces a center of an upper surface of the rotating plate;

a heating plate having a heating zone capable of controlling a temperature of any area and being located on the lower plate with a predetermined distance of the rotating plate;

a cooling plate attached to an upper surface of the upper plate ; and

a plasma excitement electrode ~~encompassing an entrance of the radial shower head by~~ being located between the cooling plate and the entrance cylinder part of the radial shower head.

2. (Currently amended) The batch type atomic layer deposition apparatus as recited in claim 1, further comprising an ion extraction electrode ~~encompassing an exhaust of the radial shower head~~ being located between the exhaust of the radial cone part of the shower head and the upper plate.

3. (Currently amended) The batch type atomic layer deposition apparatus as recited in claim 2, wherein the ion extraction electrode is supplied with a DC voltage.

4. (Currently amended) The batch type atomic layer deposition apparatus as recited in claim 1, wherein the plasma excitement electrode is constructed in a ring type structure and supplied with a RF power.

5. (Currently amended) The batch type atomic layer deposition apparatus as recited in claim 1, wherein ~~the exhaust of the radial~~ cone part of the shower head has an angle ranging from about 120° to about 160°.

6. (Currently amended) The batch type atomic layer deposition apparatus as recited in claim 1, wherein a separating distance between the radial cone part of the shower head and the rotating plate ranges from about 3.5 mm to about 7 mm.

7. (Currently amended) A method for an in-situ cleaning of a batch type atomic layer deposition apparatus with a shower head having a cylinder part and a radial cone part, the method comprising the steps of:

depositing an atomic layer on a wafer;

injecting a cleaning gas into ~~a radial~~ the shower head;

applying a RF power to a plasma excitement electrode when the cleaning gas passes through the radial ~~shower head~~ cylinder part; and

inducing a reaction between the cleaning gas activated by the plasma excitement electrode and a remnant atomic layer on a rotating plate.

8. (Original) The method as recited in claim 7, wherein the RF power of about 100 W to about 600 W is applied to the plasma excitement electrode.

9. (Currently amended) The method as recited in claim 7, wherein the cleaning gas is a mixture of Cl₂ gas and Ar gas, ~~however~~ each gas is being injected separately.